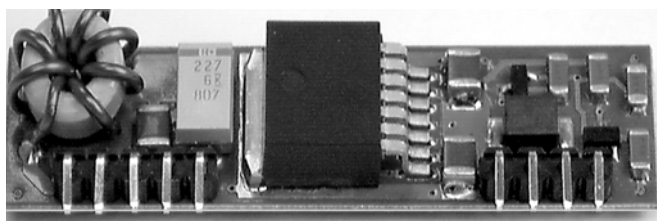


## 5V TO 3.3V, AND PROGRAMMABLE DC/DC CONVERTER WITH PARALLELABLE BOOST MODULES

### 6-PAK



#### DESCRIPTION

The 6-PAK™ is a modular system of control and boost SIPs. Each 6A control SIP can also drive up to 8 additional 6A boost SIPs in parallel, for a total of 54A. Each SIP accepts a regulated 5V input ( $\pm 10\%$ ) and provides 1.8V to 3.6Vdc output. The circuit is optimized for high efficiency and fast load transient response needed by telecom, DSP and microprocessor applications.

#### FEATURES

- **Small SIP Design**
- **Parallelable Boost SIP**  
One stocking part meets a variety of loads
- **Programmable Control SIP**  
Control/Boost Pair extremely configurable
- **Fast Transient Response**  
No need for large external capacitors  
Extremely small footprint
- **Low Component Count**  
Low cost, high reliability
- **Staked Pins**  
Wave solderable
- **Integrated Input Filter**  
Low input ripple

#### APPLICATION NOTE

- **DCAN-34 - 6-PAK Demo Board**  
Downloadable from our website -  
[cdpowerelectronics.com](http://cdpowerelectronics.com)

Advanced thermal design, monolithic power circuitry and synchronous rectification result in outstanding performance and value. With integrated input filter and output capacitors, the 6-PAK system makes a complete power supply which requires no external components over the specified operating range. Pins are staked for wave solderability.

More product information and application notes are available  
on our website at [www.cdpowerelectronics.com](http://www.cdpowerelectronics.com)

Power Electronics Division, United States  
3400 E Britannia Drive, Tucson, Arizona 85706  
Phone: 520.295.4100 Fax: 520.770.9369

Power Electronics Division, Europe  
C&D Technologies (Power Electronics) Ltd.  
132 Shannon Industrial Estate, Shannon, Co. Clare, Ireland  
Tel: +353.61.474.133 Fax: +353.61.474.141

## Electrical Specifications

Unless otherwise specified, operating conditions are as follows:  $V_{in}=5V$ ,  $V_o=3.3V$ ,  $I_o=6A$ ,  $T_A=25^{\circ}C$ ,  $C_{in}=100\mu F$ ,  $C_o=\mu F$ .

Parameter	Conditions	Min	Typ	Max	Units
Input					
Input Voltage $V_{in}$		4.5	5.0	5.5	$V_{DC}$
Input Current Ripple			200		$mA_{RMS}$
Required Capacitance $C_{in}$	Note 1	0	100		$\mu F$
Output					
Output Voltage $V_o$	Nominal	3.25	3.3	3.35	$V_{DC}$
Output Program Range	Note 2	1.8		3.6	$V_{DC}$
Output Current $I_o$	$T_A=25^{\circ}C$	0		6	Amps
Output Ripple	20Mhz BW			50	mVp-p
Output Rise Time $T_r$			12		$\mu S$
Output Capacitance Range $C_o$		0		5000	$\mu F$
Line Regulation			$\pm 0.5$		%
Load Regulation	$I_o \text{ min} - I_o \text{ max}$		$\pm 0.5$		%
Temperature Coefficient $T_c$			0.01		%/ $^{\circ}C$
Combined Variation	$V_{in} \text{ min-max \&/or } I_o \text{ min-max}$ $T_A=25^{\circ}C - 85^{\circ}C$	-2		+2	%
Protection	Note 3				
General					
Switching Frequency			800		kHz
Dynamic Response					
$\Delta I_o / \Delta t = 1A/10\mu \text{ sec}$ , $V_i = 5.0V$ , $T_A = 25^{\circ}C$					
Load Change from $I_o = 0\%$ to $I_o = 100\%$			60		mV
Peak Deviation			150		$\mu \text{sec}$
Settling time ( $V_o < 10\%$ Peak Deviation)					
Load change from $I_o = 100\%$ to $I_o = 0\%$			90		mV
Peak Deviation			100		$\mu \text{sec}$
Settling time ( $V_o < 10\%$ Peak Deviation)					
Temperature					
Operating Temperature		Note 4		+60	$^{\circ}C$
Storage Temperature		-40		+125	$^{\circ}C$

### Notes

1. Input source <3" from 6-PAK™, load transient <3A per SIP. 100 $\mu F$  low ESR capacitor for load transients >3A per SIP.
2. Optional programming 1.8 - 3.6 or  $\pm 10\%$  available. See Table.
3. Short circuit and thermal protection.
4. 100 lfm air,  $V_o=3.3V$ ,  $I_o=6A$ . See Thermal Design Guide for other conditions.

## Programming

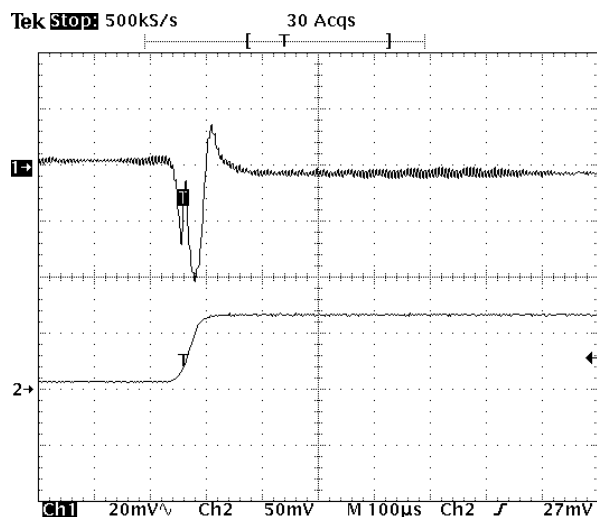
The 6-PAK™ is programmed through the Control SIP. All connected Power Boosters follow the Control SIP programming. To program the 6-PAK™ for  $V_{out} < 3.3$ , connect a resistor across the TRIM and  $V_o$  pins. For  $V_{out} > 3.3$ , resistor is connected across TRIM and GND.

**Table 2**

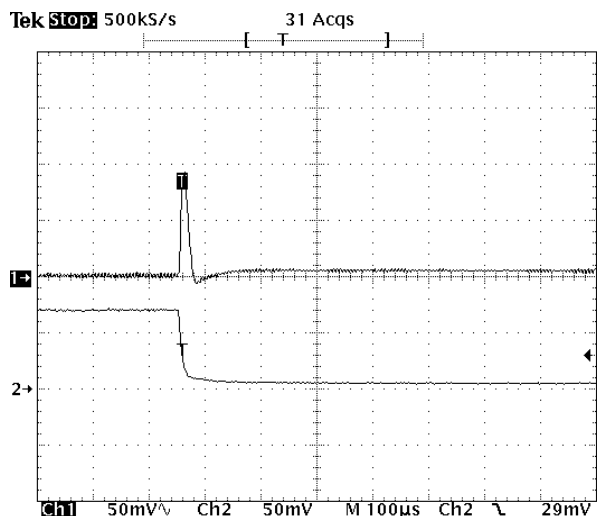
$V_{out}$	Resistor Value	$V_{out}$	Resistor Value
1.8	0Ω	2.8	442Ω
1.9	15.6Ω	2.9	604Ω
2.0	34Ω	3.0	866Ω
2.1	55.6Ω	3.1	1.37k
2.2	80.6Ω	3.2	2.80k
2.3	110Ω	3.3	Open
2.4	147Ω	3.4	2.32k
2.5	196Ω	3.5	1.00k
2.6	255Ω	3.6	649Ω
2.7	332Ω		

## Transient Response

Operating conditions are as follows:  $V_{in}=5V$ ,  $V_o=3.3V$ , Load change from  $I_o=0\%$  to  $I_o=100\%$ ,  $T_A=25^\circ C$ ,  $C_{in}=0F$ ,  $C_o=\mu F$ .



Operating conditions are as follows:  $V_{in}=5V$ ,  $V_o=3.3V$ , Load change from  $I_o=100\%$  to  $I_o=0\%$ ,  $T_A=25^\circ C$ ,  $C_{in}=0F$ ,  $C_o=\mu F$ .

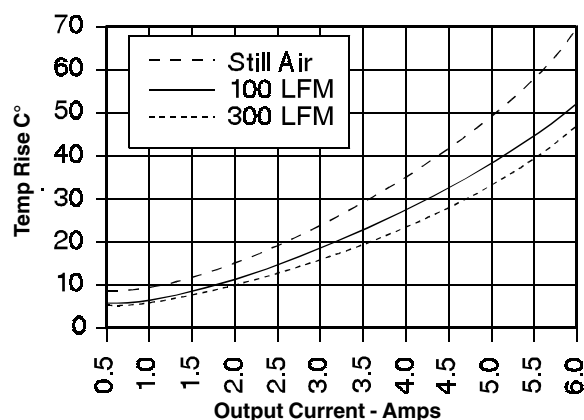


## Thermal Design Guide

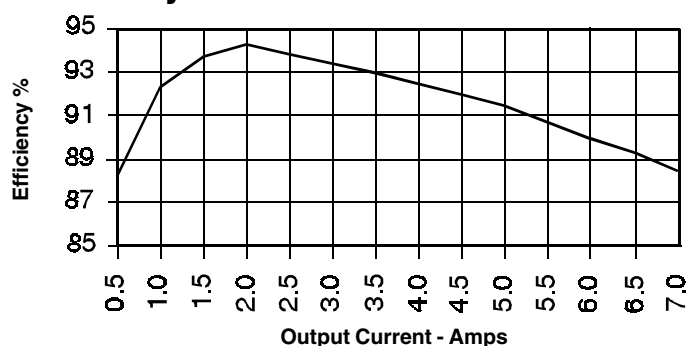
Locate your operating current, read the junction temp rise from the graph and add to your maximum ambient.  $135^\circ C$  is the maximum allowable operating junction temperature. Test conditions: Device soldered into 4" X 4" PCB, 2-sided with power and ground planes for heat conduction. Due to the difficulty in predicting the thermal effects of airflow velocity and direction, and thermal conduction through ground planes, it is important that the 6-PAK™ be evaluated thermally in each application. For high ambient temperature/high current application, please request our Application Note, "Accurate Measurements of 6-PAK™ Junction Temperature."

### $T_j$ Rise vs. $I_o$

(Junction Temp Rise vs. Output Current)



### Efficiency

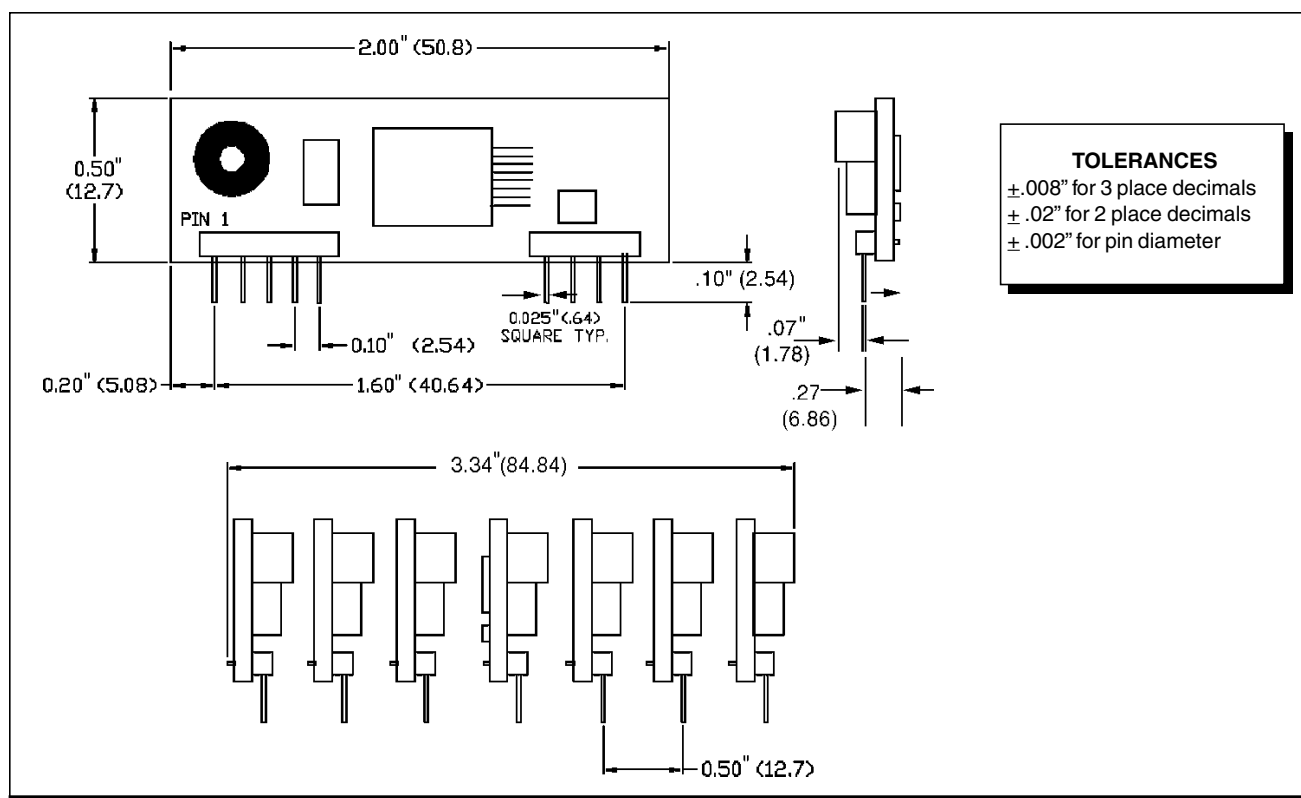


## Ordering Information

Typical examples:

6P	25	-	C	6A Control SIP
6P	25	-	P	6A Power Booster SIP

## Mechanical Outline



## Pin Out

Pin	Function	Description
1	V <sub>o</sub>	Output Voltage
2	V <sub>o</sub>	Output Voltage
3	TRIM	Output Adjust*
4	GND	Ground
5	INT1	InterModule 1
6	Gnd	Ground
7	INT2	InterModule 2
8	V <sub>i</sub>	5V Input Voltage
9	V <sub>i</sub>	5V Input Voltage

\* not connected on Boosters

## System Interconnection Guidelines

1. Each SIP must have input, ground and output pins sunk into common input ground and output planes in the host PC board.
2. Two additional common signal traces are required to interconnect INT1 and INT2 pins. These traces must be at least 0.06" wide and make a straight connection among the modules.
3. Power Booster SIP must be adjacent to the Control SIP located in the center of the layout, as shown in the Typical Example figure. Recommended distance between SIP pin centers is 0.5".

Standard Options are shown, consult factory for other available options.

The information provided herein is believed to be reliable; however, C&D TECHNOLOGIES assumes no responsibility for inaccuracies or omissions. C&D TECHNOLOGIES assumes no responsibility for the use of this information, and all use of such information shall be entirely at the user's own risk. Prices and specifications are subject to change without notice. No patent rights or licenses to any of the circuits described herein are implied or granted to any third party. C&D TECHNOLOGIES does not authorize or warrant any C&D TECHNOLOGIES product for use in life support devices/systems or in aircraft control applications.